



HT882

NPN EPITAXIAL PLANAR TRANSISTOR

Description

The HT882 is designed for using in output stage of 1w audio amplifier, voltage regulator, DC-DC converter and relay driver.

Absolute Maximum Ratings (Ta=25°C)

- Maximum Temperatures
Storage Temperature -55 ~ +150 °C
Junction Temperature +150 °C Maximum
- Maximum Power Dissipation
Total Power Dissipation (Ta=25°C) 1 W
Total Power Dissipation (Tc=25°C) 10 W
- Maximum Voltages and Currents
BVCBO Collector to Base Voltage 40 V
BVCEO Collector to Emitter Voltage 30 V
BVEBO Emitter to Base Voltage 5 V
IC Collector Current (DC) 3 A
IC Collector Current (Pulse) 7 A
IB Base Current (DC) 0.6 A

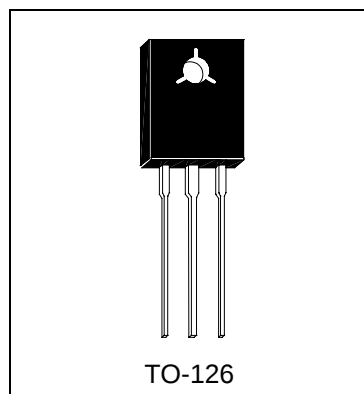
Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	40	-	-	V	IC=100uA
BVCEO	30	-	-	V	IC=1mA
BVEBO	5	-	-	V	IE=10uA
ICBO	-	-	1	uA	VCB=30V
IEBO	-	-	1	uA	VEB=3V
*VCE(sat)	-	0.3	0.5	V	IC=2A, IB=0.2A
*VBE(sat)	-	1	2	V	IC=2A, IB=0.2A
*hFE1	30	150	-		IC=20mA, VCE=2V
*hFE2	100	200	500		IC=1A, VCE=2V
fT	-	90	-	MHz	IC=0.1A, VCE=5V
Cob	-	45	-	pF	VCB=10V, f=1MHz, IE=0

*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%

Classification Of hFE2

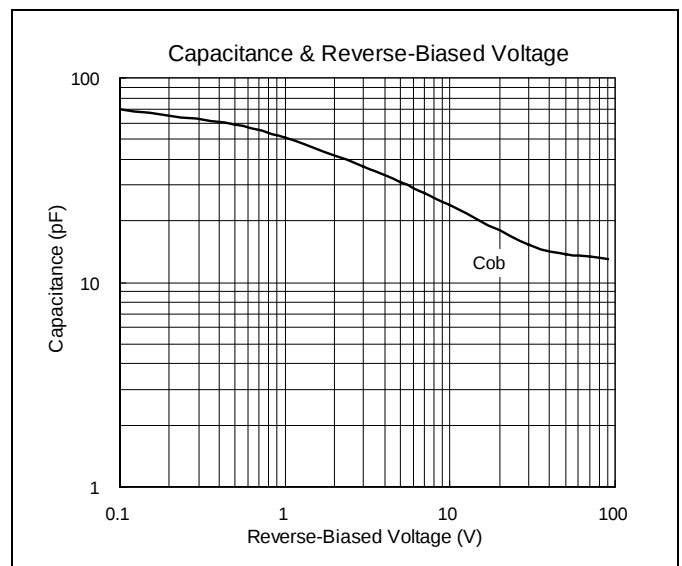
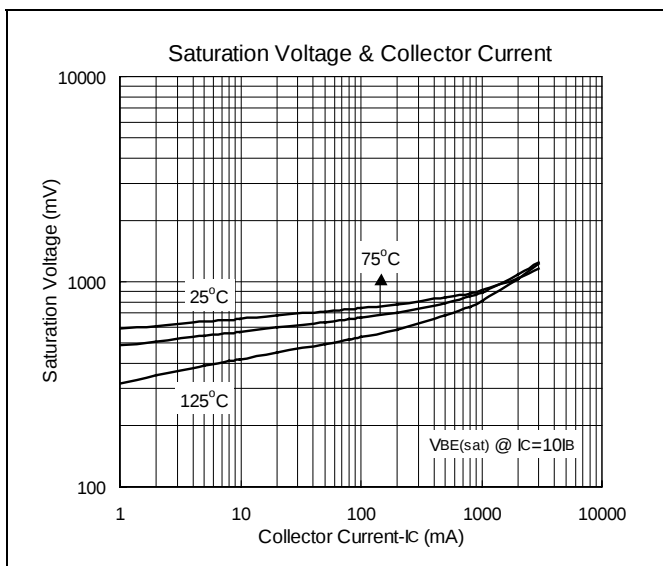
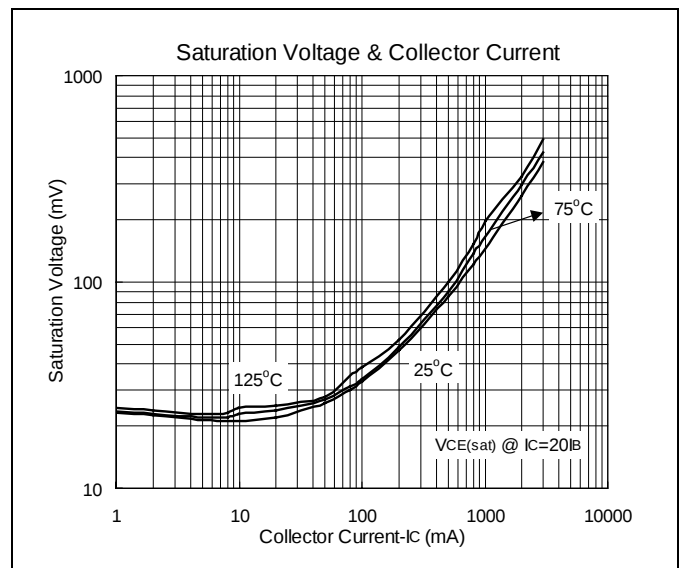
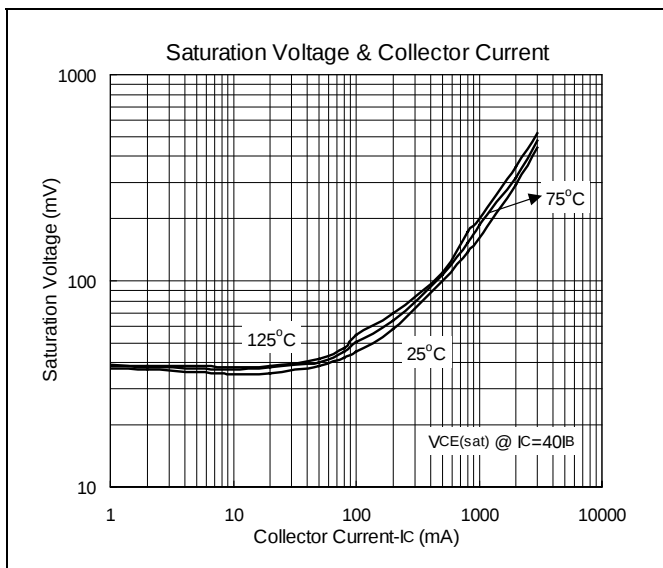
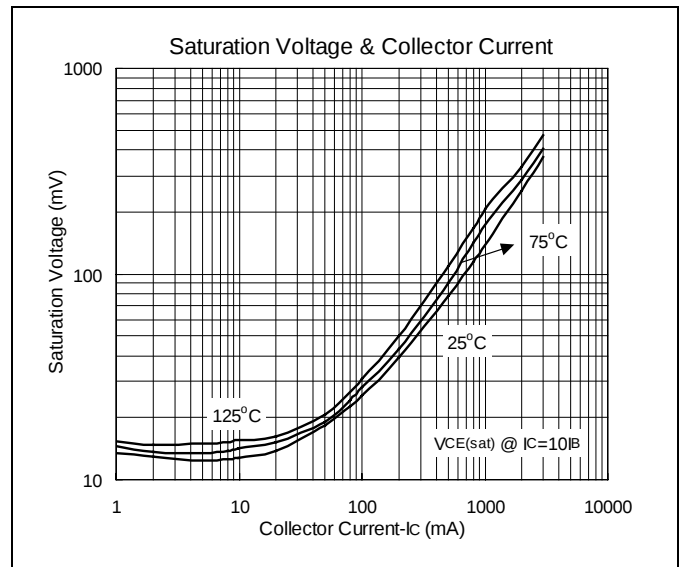
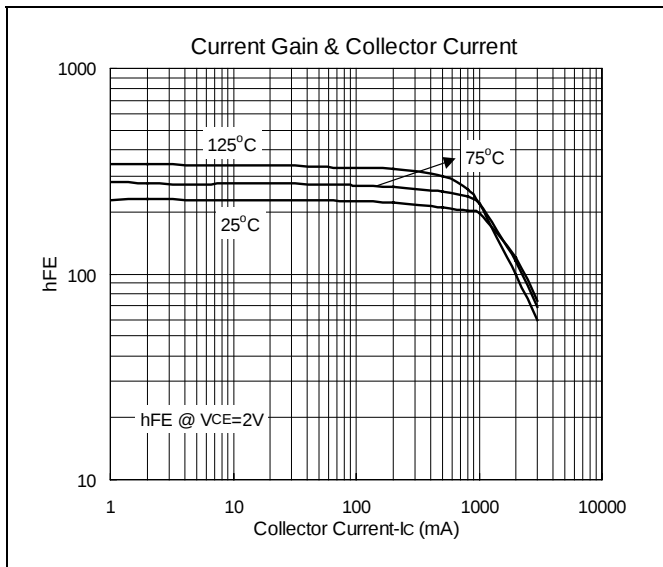
Rank	Q	P	E
Range	100-200	160-320	250-500

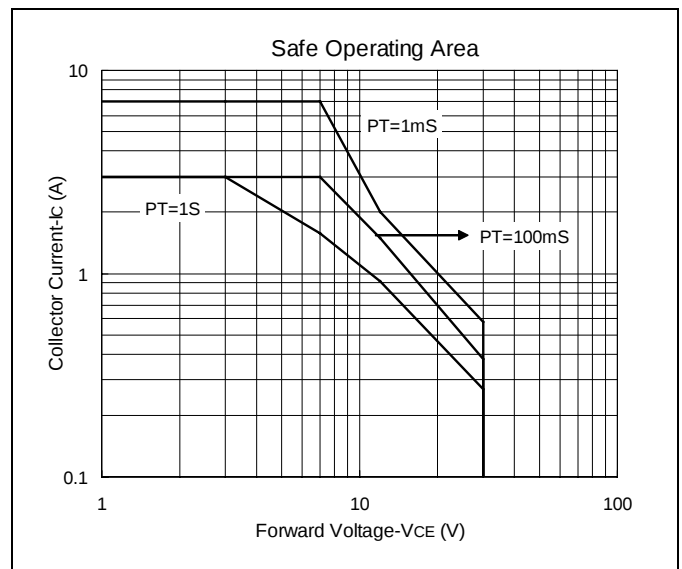
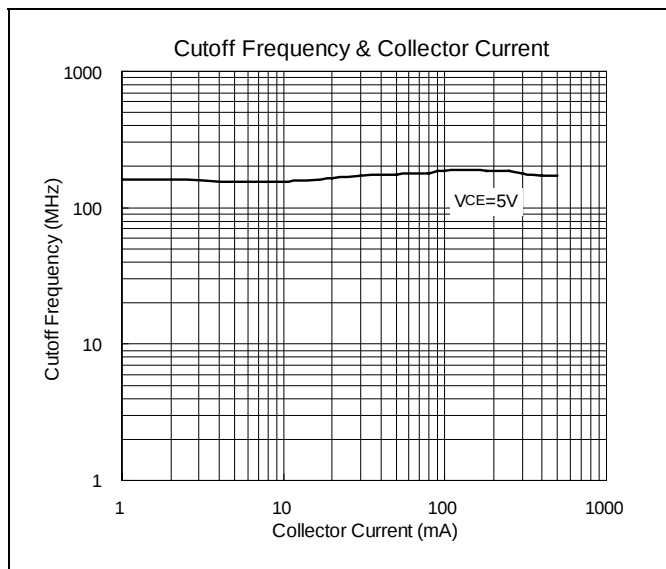


TO-126



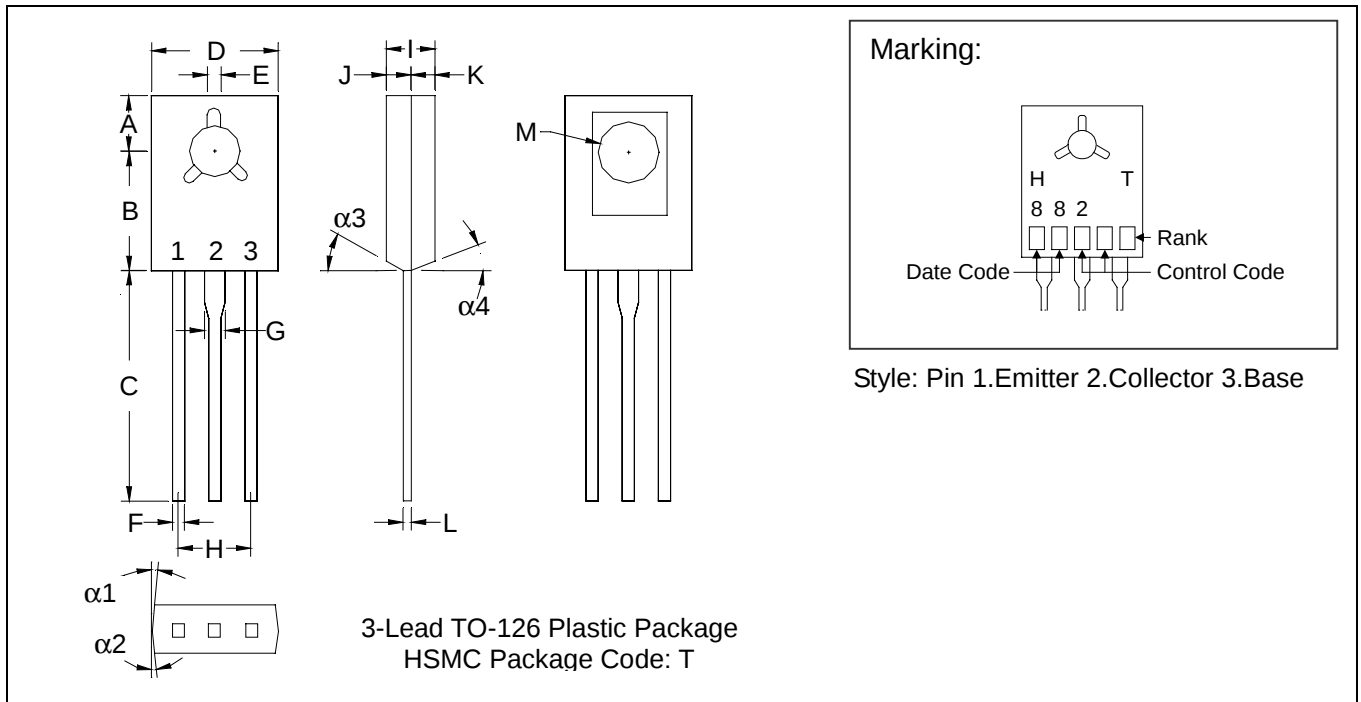
Characteristics Curve







TO-126 Dimension



*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
$\alpha 1$	-	*3°	-	*3°	F	0.0280	0.0319	0.71	0.81
$\alpha 2$	-	*3°	-	*3°	G	0.0480	0.0520	1.22	1.32
$\alpha 3$	-	*3°	-	*3°	H	0.1709	0.1890	4.34	4.80
$\alpha 4$	-	*3°	-	*3°	I	0.0950	0.1050	2.41	2.66
A	0.1500	0.1539	3.81	3.91	J	0.0450	0.0550	1.14	1.39
B	0.2752	0.2791	6.99	7.09	K	0.0450	0.0550	1.14	1.39
C	0.5315	0.6102	13.50	15.50	L	-	*0.0217	-	*0.55
D	0.2854	0.3039	7.52	7.72	M	0.1378	0.1520	3.50	3.86
E	0.0374	0.0413	0.95	1.05					

Notes: 1.Dimension and tolerance based on our Spec. dated Mar. 6,1995.

2.Controlling dimension: millimeters.

3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.

4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material:

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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Head Office And Factory:

• **Head Office** (Hi-Sincerity Microelectronics Corp.): 10F., No. 61, Sec. 2, Chung-Shan N. Rd. Taipei Taiwan R.O.C.
Tel: 886-2-25212056 Fax: 886-2-25632712, 25368454

• **Factory 1:** No. 38, Kuang Fu S. Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C
Tel: 886-3-5983621~5 Fax: 886-3-5982931